

Kamlesh Joshi

List of Publications by Year in descending order

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Version: 2024-02-01

10
papers

94
citations

1937685

4
h-index

1588992

8
g-index

10
all docs

10
docs citations

10
times ranked

81
citing authors

#	ARTICLE	IF	CITATIONS
1	Comparative electrical characterization of spark-erosion of silicon and steel as a base and its implications on equivalent circuit. <i>Materials Science in Semiconductor Processing</i> , 2022, 137, 106199.	4.0	0
2	Identification of wire electrical discharge machinability of SiC sintered using rapid hot pressing technique. <i>Ceramics International</i> , 2020, 46, 17261-17271.	4.8	11
3	Influence of open voltage and servo voltage during Wire-EDM of silicon carbides. <i>Procedia CIRP</i> , 2020, 95, 285-289.	1.9	4
4	Experiments with Miniature Wire EDM for Silicon. <i>Procedia CIRP</i> , 2020, 95, 296-301.	1.9	2
5	Surface integrity and wafer-thickness variation analysis of ultra-thin silicon wafers sliced using wire-EDM. <i>Advances in Materials and Processing Technologies</i> , 2019, 5, 512-525.	1.4	3
6	Surface Quality and Contamination on Si Wafer Surfaces Sliced Using Wire-Electrical Discharge Machining. <i>Journal of Engineering Materials and Technology, Transactions of the ASME</i> , 2019, 141, .	1.4	7
7	Microstructural Characterization of Thermal Damage on Silicon Wafers Sliced Using Wire-Electrical Discharge Machining. <i>Journal of Manufacturing Science and Engineering, Transactions of the ASME</i> , 2018, 140, .	2.2	17
8	Numerical Modelling of Wire-EDM for Predicting Erosion Rate of Silicon. <i>Journal of the Institution of Engineers (India): Series C</i> , 2017, 98, 63-73.	1.2	4
9	Ultra thin silicon wafer slicing using wire-EDM for solar cell application. <i>Materials and Design</i> , 2017, 124, 158-170.	7.0	45
10	Effect of Deposition Parameters & Molybdenum Percentage on Nickel-Molybdenum Alloy Coatings. <i>Advanced Materials Research</i> , 0, 585, 493-497.	0.3	1